

REMARKS

I. Status of the Application

In the March 5, 2003 Notice of Non-Compliant Amendment, the Examiner has requested a clean version of claim 17. In this response, Applicant has provided a clean revision of claim 17.

II. Conclusion

It is respectfully submitted that all claims are in condition for allowance. Accordingly, prompt and favorable examination is earnestly solicited.

Respectfully Submitted,



Harold C. Moore  
Attorney for Applicant  
Attorney Registration No. 37,892  
Maginot, Moore & Bowman  
Bank One Center/Tower  
111 Monument Circle, Suite 3000  
Indianapolis, Indiana 46204-5115  
Telephone: (317) 638-2922

**APPENDIX**

Pursuant to 37 C.F.R. Section 1.121(c)(1)(ii), below are the changes to claim 17.

17. (amended) A method of fabricating a semiconductor wafer, comprising:

(a) subjecting said semiconductor wafer to a pressure; and

(b) measuring said pressure said semiconductor is subjected to with a pressure measurement device supported on said semiconductor wafer, said pressure measurement device including (i) a capacitor, (ii) capacitance measurement circuitry electrically coupled to said capacitor, and (iii) capacitance to pressure conversion circuitry electrically coupled to said capacitance measurement icruity, and further including converting a capacitance of said capacitor to a pressure with said capacitance to pressure conversion circuitry.